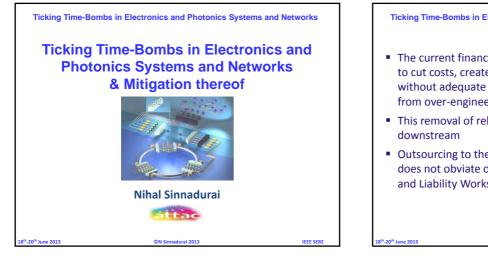
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Ticking Time-Bombs in Electronics and Photonics Systems and Networks

- The current financial and survival pressures on companies to cut costs, creates an environment to release products without adequate reliability assurance (we have moved from over-engineering to under-qualifying)
- This removal of reliability assurance creates serious risks downstream
- Outsourcing to the ignorant aggravates the problem and does not obviate ownership of liability (IEEE Reliability and Liability Workshop)

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• Symptoms are starting to show:

even the great history of cost-effective reliability of electronics is being dented by failures, now appearing, of outsourced and cheap manufactured products

- network outages are occurring
- The track record of enduring high reliability of components' will cease if OEMs continue to dumb-down
- Products so delivered are time bombs when installed in networks, requiring that the networks be more robust and fault tolerant and over-engineered (system mitigation).

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Public domain examples of "Qualification" that did not provide Reliability Assurance:

Fujitsu HDDs; 3.5-inch HDDs mounted internally in PCs failed to spin up.
Cirrus Logic: drive controller, IC package failed.
XXX Corp: failures in its analog IC test systems

One manufacturer commented: "It's something that cannot be detected by existing reliability tests"

These publicly known examples are just the tip of the iceberg. There are many private arbitration cases resulting from unreliable product failures that have led to major compensation

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Most equipment and IC manufacturers perform "standard" reliability tests on new devices and technologies.

Exception: Bookham Technology plc, whose reliability engineers were trained to assess the validity of 'standards', to extract the relevant clauses and durations and to develop 'fit for purpose' methods and Reliability Assurance plans and Qualification plans.

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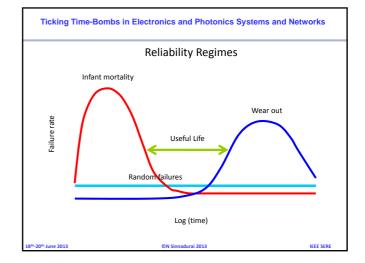
### **Reliability non-Assurance**

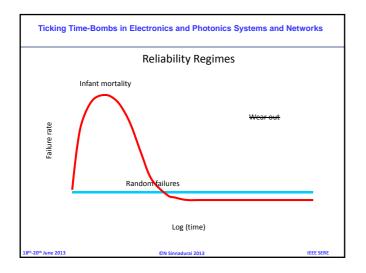
- There is non-practitioner ignorance that products are not identical and that processes may develop flaws that are not trackable by, or responsive to, quality control.
- Desk-based 'simulation' using theoretical 'data' to predict reliability and release products into use without the essential practical and statistically valid information.
- Dumbing-down of reliability 'standards' makes them inadequate for high reliability systems.
- Products so 'qualified' can be time bombs when installed in networks, requiring that the networks be more robust and fault tolerant and over-engineered.

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Reliable operation requires assurance that products will not fail early or at an unacceptable rate during useful life or degrade and cause system failures before the required lifetime is required.

- Reliability assurance is not an exact science
- The only <u>certain</u> assurance is obtained by operating the full population over the required lifetime and obtaining data with hindsight.
- This is impractical
- Therefore, reliability is assured by infant mortality screening and 'accelerated ageing' whereby statistically significant samples extracted from the manufactured population are subjected to specific 'overstress' tests in accordance with proven relationships ('models') for the predetermined durations, i.e. 'Evidence based reliability'





Ticking Time-Bomb	s in Electronics and Photonics System	ms and Networks
The causes of hard	ware component unreliability are	not 'in your face'.
They can be subtle	as:	
<ul> <li>oxide or pa</li> </ul>	ssivation stress,	
<ul> <li>proton incl</li> </ul>	usions in nitrides or inclusions of e	extremely low
levels of io	nic elements incorporated into the	e bulk
semicondu	ctor to form charge or recombinat	ion centres at
the junctio	ns	
<ul> <li>the dissolu</li> </ul>	tion of a small quantity of gold inte	o a lead-tin
solder joir	nt due to the wrong specification for	or plating or a
minor proc	ess glitch, causing brittle joints	
<ul> <li>an unknow</li> </ul>	n Pb and Pb-free combination in t	he solder joints
- a variation	of 0.1% of the accelerator of an ac	dhesive
preventing	a full and lasting cure	
<ul> <li>a curing ov</li> </ul>	en being timed the wrong way	
These may look an	d perform perfectly well in quality	control, but will
progressively degra	ade the product in time	
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Partitioned code from disparate sources is integrated and correctly managed under configuration management (i.e. interdependences). This ensures that the impact of changes of code are traceable. Assurance against faulty code is by validation and verification testing. In principle, test sequences could be infinite to ensure all code is exercised. This is not practical. So, there is always risk. It can be quantified. Strictly, this is a measure of quality, although the encounter with the faulty code downstream allows it to be called software reliability. Ticking Time-Bombs in Electronics and Photonics Systems and Networks

Genuine degradation arises from damage/degradation of cells of a memory. A cause of damage arises from Radiation (space or package sourced) penetrating the cells. Rad upsets do not lend themselves to quality control. Radiation hardness can be built-in, designed-in or achieved by shielding. Rad hardness can be verified by exposure to particular doses for specified times.

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- Processes performing within the predetermined statistical process control parameters can still affect reliability.
- Such variations are detected by ongoing vigilance through Maintenance of Qualification (MoQ) by ongoing sampling from production and reliability testing.

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- Mitigation of soft faults is achievable using circuit hardening techniques, e.g. Built-in Soft Error Resilience. BISER implements two redundant memory elements and a C-element at the output (increased hardware) to block error propagation. This has advantage over Dual interlocked cell (DICE) schemes.
- Because code does not wearout, MoQ is not relevant. Changes in code must of course be validated and verified.
- Rad hard devices must be subjected to MoQ

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So, what is "Qualification"?

- For hardware, it is the formal legal demonstration of survival to a series of stress tests conforming to recognised international standards, during which specific characteristics are measured to determine the product behaviour within or beyond the specified end-of-life limits (Black box approach).
- In the photonics industry, the established standards are those drafted by Telcordia (formerly BellCORE). More recently IEC is increasingly favoured by the telecommunications service providers.
- In the electronics industries the standards are IEEE, JEDEC, IEC, CECC, EIA, AEC, MIL (MIL is less authoritative)

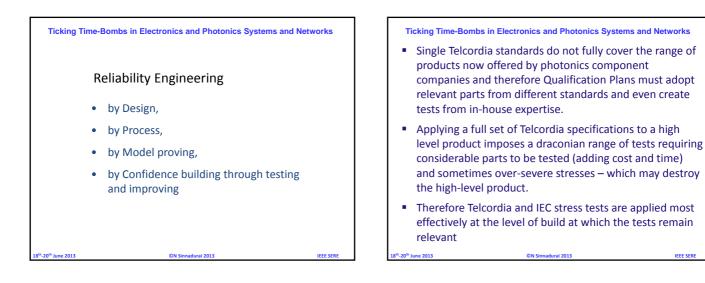
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- The standards do not absolve the supplier company from proving that their products are fit-for-purpose. Hence the need for long term reliability assessment.
- Because qualification tests and reliability tests of hardware are intended to consume actual life, and demonstrate the product does not fail, such tests are deemed "destructive", i.e. the components cannot be sold on (as some non-technical executives seem to expect).

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 Transponder

 Qualification plan

 Packaged

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A structured example of a Product Qualification build-up is by assuring the elements (blocks) of a full system and thereby creating a library of qualified

Building Blocks. The alternative to this approach is to Qualify all legs of the full product at the top level which will be extremely expensive, time consuming and some of the tests will probably destroy the

### Calibre of evidence: Electronics

product.

In the High-Rel Telecommunications industry, the reliability of electronics and microelectronics was achieved by applying a range of overstress tests based on well characterised models of ageing and sampled to a required statistical standard of better than 1% LTPD (Lot Tolerance Percent Defective) which is a measure of the statistical confidence in the result. Typically, 235 electronics devices are overstress tested per test condition (i.e. total devices reliability tested per qualification > 1500) Ticking Time-Bombs in Electronics and Photonics Systems and Networks

### Technical Evidence

The correct equation (model) for Highly Accelerated Stress Testing (HAST):  $t_{amb}/t_s=exp\{X[(RH_s)^n-(Rh_{amb})^n] + (E_A/k)(1/T_{amb}-1/T_s)\}$ 

Verified by 150 x 10 $^{6}$  device hours of practical stress testing

When applied to semiconductor devices, the empirical S-H Model expression is:

 $t_s = 175000/exp\{0.00044[(RH_s)^2 - (Rh_{amb})^2] + 7000(1/T_{amb} - 1/T_s)\}$ 

where 175000 hours is 20 years and is the required lifetime  $(t_{amb})$ at the ambient condition, RH<sub>s</sub> is the applied humidity stress, RH<sub>amb</sub> is the humidity at the application ambient, T<sub>s</sub> is the applied stress absolute temperature and T<sub>amb</sub> is the application ambient temperature, E<sub>A</sub> is the activation energy for the specific failure mechanism, X is the humidity activation coefficient and "n" is the humidity activation exponent

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Ticking Time-E	Bombs in Electronics an The operating	d Photonics Systems and environments	Networks
		TING CLIMATES m reliability)	
	Region	Climate	
	Temperate (Europe, North America)	12 <sup>0</sup> C & 72% RH	
	Sub-tropical (99% of locations)	29ºC & 86%RH	
	Full tropical (Rainforest regions)	35 <sup>0</sup> C & 90% RH	
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	Genera	ating the	e eviden	ice	
THB Reliability test	s for 20 yea	r survival i	n different	climatic cor	nditions
		The overstre	ss conditions	to be applied	
	85°C &	95°C &	108°C &	125°C &	125°C &
	85%RH	95%RH	90%RH	90%RH	95%RH
"Uncontrolled" average	Humidity	Humidity			
operating climate	chamber	chamber	HAST	HAST	HAST
Ų	Time (hrs)	Time (hrs)	Time (hrs)	Time (hrs)	Time (hrs)
Temperate general (12°C & 72%RH)	500	130	100	50	Too short
Tropical coverage of 99% of sub-tropics (29°C & 86%RH)	5100	1300	1000	500	320
Tropical severe (35°C & 90%RH)	10000	2600	2000	950	630
	Base	d on the S-H	nodel		
	Base	d on the S-H	nodel		
e 2013		©N Sinnadurai 2	012		

Ticking Time-Bombs in Electronics and Photonics Systems and Networ	ks

# Ignorance or Cavalier?

WARM & DAMP CLIMATE HARDWARE RELIABILITY ASSURANCE

But, is one condition valid for all?

Massive errors arise by assuming the wrong activation energy or wrong S-H Humidity Coefficient.

## HAST ACCELERATION FOR 0.9eV AND 0.6eV ACTIVATION ENERGIES FOR

Activation Energy	Base Station	Calculated	Predicted Lifetime
eV	Environment	Acceleration Factor	for 96 hour test
0.9	70°C & 15% RH	2020	194000 (22.1 years)
0.9	70°C & 16% RH	1990	191000 (21.8 years)
0.9	50°C & 41% RH	7100	673000 (77 years)
0.6	70°C & 15% RH	455	43700 (5.0 years)
0.6	70°C & 16% RH	450	43200 (4.9 years)
0.6	50°C & 41% RH	850	82000 (9.4 years)
0.6	50°C & 41% RH	850	82000 (9.4 years)
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## Dangerous irrelevance

Vendor	Mil-Hdbk-217 MTTF (hrs)	Observed MTTF (Hours
А	7247	1160
В	5765	74
С	3500	624
D	2500	2174
Е	2500	51
F	2000	1056
G	1600	3612
Н	1400	98
Ι	1250	472

Ticking Time-Bombs in Electronics and Photonics Systems and Networks

- The LTPD of a sampling plan determines the level of faults that may escape detection when manufactured parts are subjected to quality or reliability tests.
- It is generally defined as the percent defective (number of defectives per hundred units X 100%) that the sampling plan will permit 90% of the time.

Max %				FD 3	ampii	ng Tal	ne	-			
Defective	20%	15%	10%	7%	5%	3%	2%	1.5%	1%	0.7%	0.5%
Acceptance Number (c); rejects=c+1		-		Mini	mum	Sample	e Size	Needeo	ł		2
	11	15	22	32	45	76	116	153	231	328	461
				*					<u>.</u>	9	

Ticking Time-Bombs in Electronics and Photonics Systems and Networks

Recent calibre of evidence:

With photonics products and recent poor practise by some microelectronics companies, the cost reduction regimes have led to a poor level of statistical sampling resulting in an LTPD of 20%, arising from the qualification testing of only 11 devices <u>per overstress condition</u> (no failures permitted).

Ticking Time-Bombs in Electronics and Photonics Systems and Networks It is a legal obligation to declare and report on all components placed on test and all failures that occur. Padding the population is practiced in the industry to achieve the minimum of 11 survivors. However, strictly, all failures must be reported. Note that 1 failure in less than 18 devices does constitute qualification failure of even the low statistical demands of these products.

Qualification reports globally are strewn with reports to excuse specific failures (e.g. "fibre inadvertently broken during handling for measurement" "cause of failure not due to device" ???).

This is a new breed of CEO-driven 'reliability engineer'

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#### **Another CEO-driven pressure**

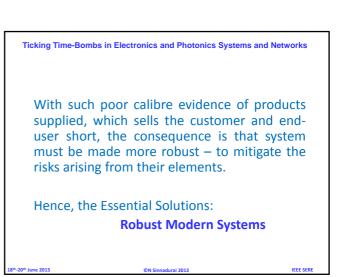
Software in products: 'I have paid the coders to write good code. We have no need, budget or time for test code development or additional testing. Get the damn product shipped' Ticking Time-Bombs in Electronics and Photonics Systems and Networks

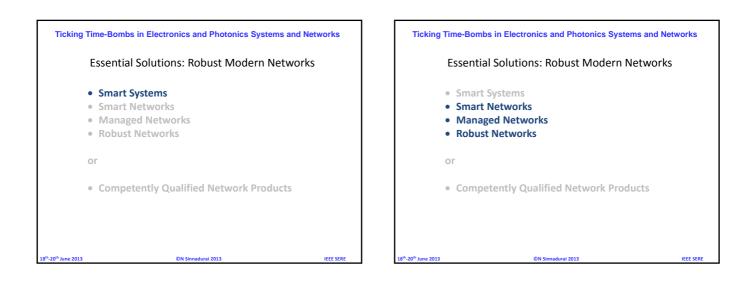
The parameter for System Reliability = the FIT

- 1 FIT = 1 Failure in 10<sup>9</sup> Device Hours
- Why?
- Because major systems use millions of components required to function 10-20 years (hundreds of thousands of hours) with few failures.
- Therefore the failure rates must be in parts per billion device hours. Even small failure rates will lead to frequent equipment failures and cause significant down-times and high maintenance costs
- So, the calibre of evidence gathering must be robust and not dumbed down!

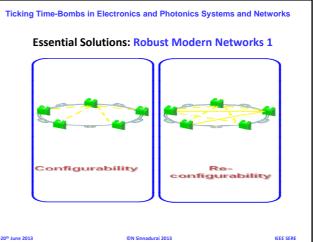
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Duration	Sample Size	Actual Failures	CL	FIT Estimate	Comments
5000	11	0	60	16728	Typical "standard" life test low sample size gives high FIT rate
5000	368	0	60	500	High reliability sample size to achieve 500 FITs at 60% CL

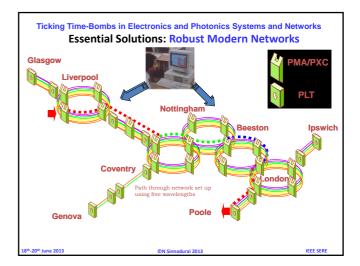


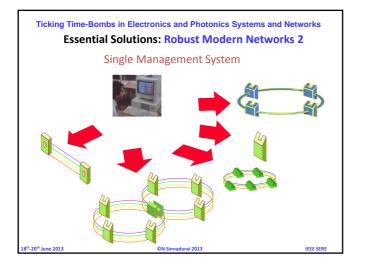


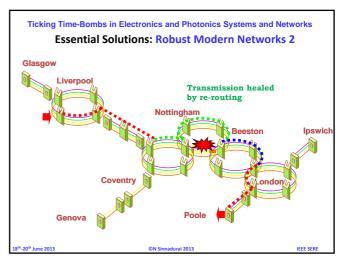
Ticking Time-Bombs in Electronics and Photonics Systems and Networks Essential Solutions: Robust Modern Networks 1 Primary protection is intended to be rapid and is based either on built-in redundancy or through real-time dynamically reconfigured mesh using cross-connect . This provides for fast resilience in the event of concurrent outages. Mesh involves high connectivity in which the protection paths are shared and is therefore dependent on availability. 18"-20" June 2013 LEE SEE

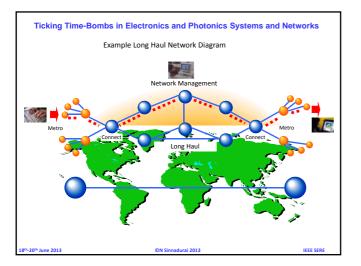


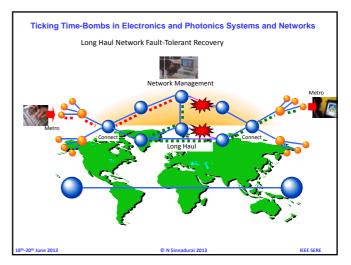
Ticking Time-Bombs in Electronics and Photonics Systems and Networks **2** Essential Solutions: Robust Modern Networks **2** Secondary protection provides back-up in the event that primary protection fails to deliver 100% restoration. Secondary restoration can be achieved through the control plane and can adapt to outages by reconfiguring and reusing available capacity in the network. Accordingly, the provision of such protection requires that network intelligence is collected dynamically.











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IN driven packetised voice
Rapid growth from 200 to 350 SW engineers
Interviewed for skills, responsibility and integrity
Rapid growth from 200 to 350 SW engineers Interviewed for skills, responsibility and integrity System Requirements objective-driven partitioned by supervising team. All interfaces specified Requirement included whole life robustness from external attack. Partitioned development in teams, tested, integrated, tested. Placed under configuration management (manage hierarchical
Requirement included whole life robustness from external
Partitioned development in teams, tested, integrated, tested.
Placed under configuration management (manage hierarchical
impact of changes)
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